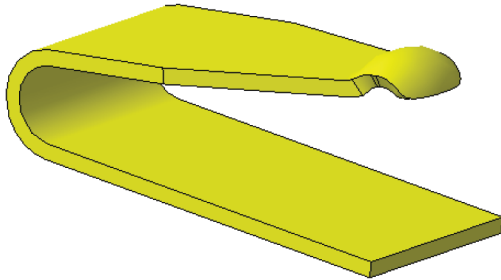


C-Clip Connector

Pulse Part Number W9908



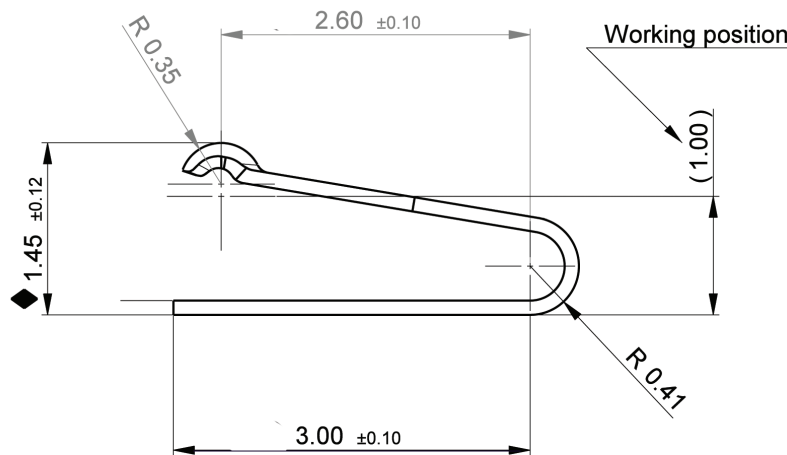
Ideal for board-to-antenna applications
Spring contact for positive connection
Surface mount technology; solder reflowable

Features

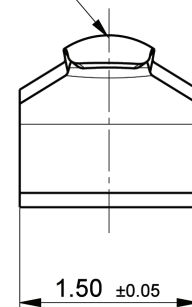
- PWB Footprint 3.2 x 1.7 mm
- Nominal Contact Height 1 mm
- Tape & Reel Packaging
- RoHS Compliant Product

Applications

- Antenna Contacts



No burr on this side

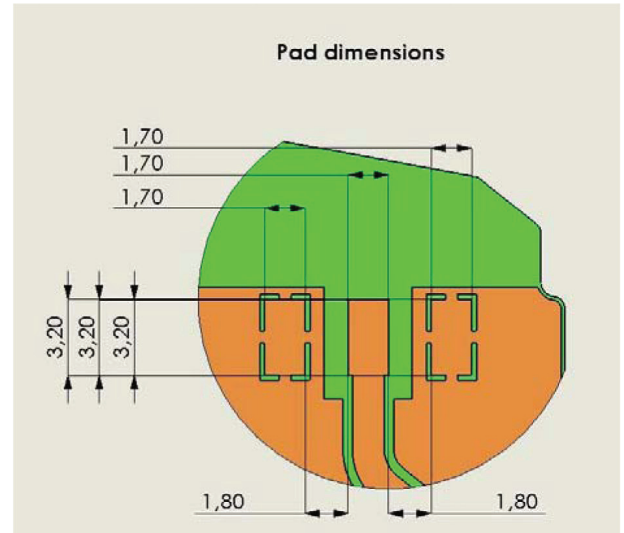
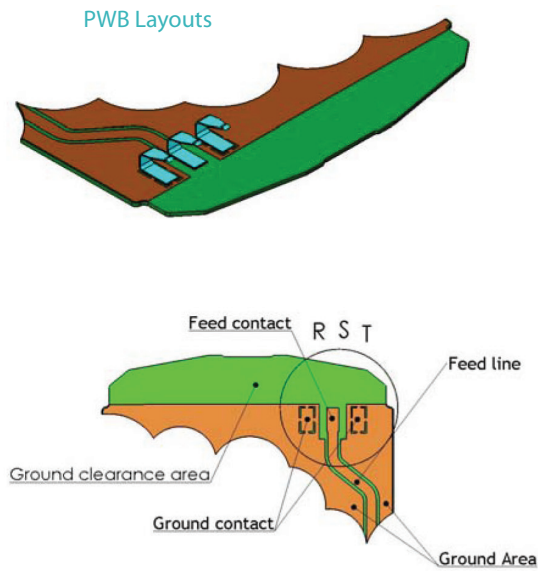


C-Clip Connector

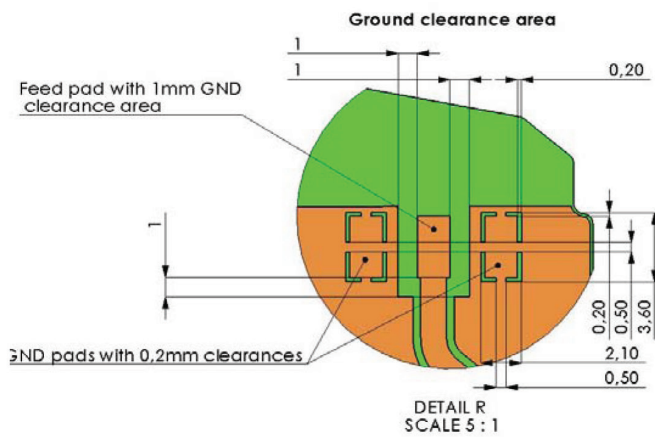
Pulse Part Number W9908

W9908 C-Clip Configuration and Dimensions

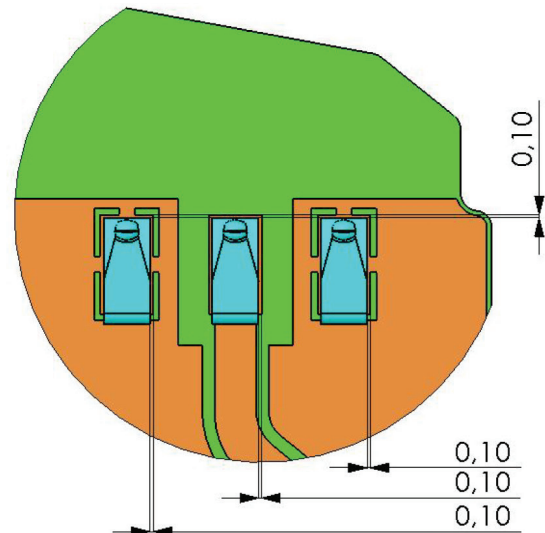
PWB Footprint Dimensions and C-Clip Position for W9908



Ground Clearance Area for W9908 C-Clip



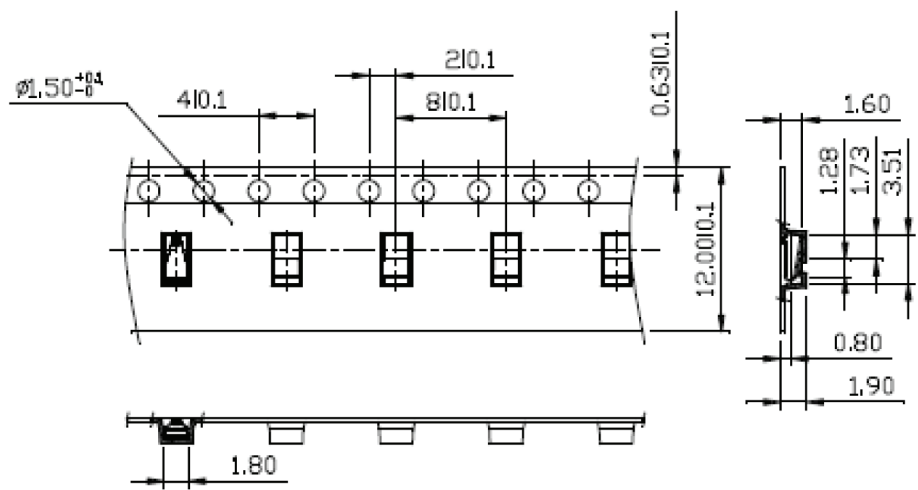
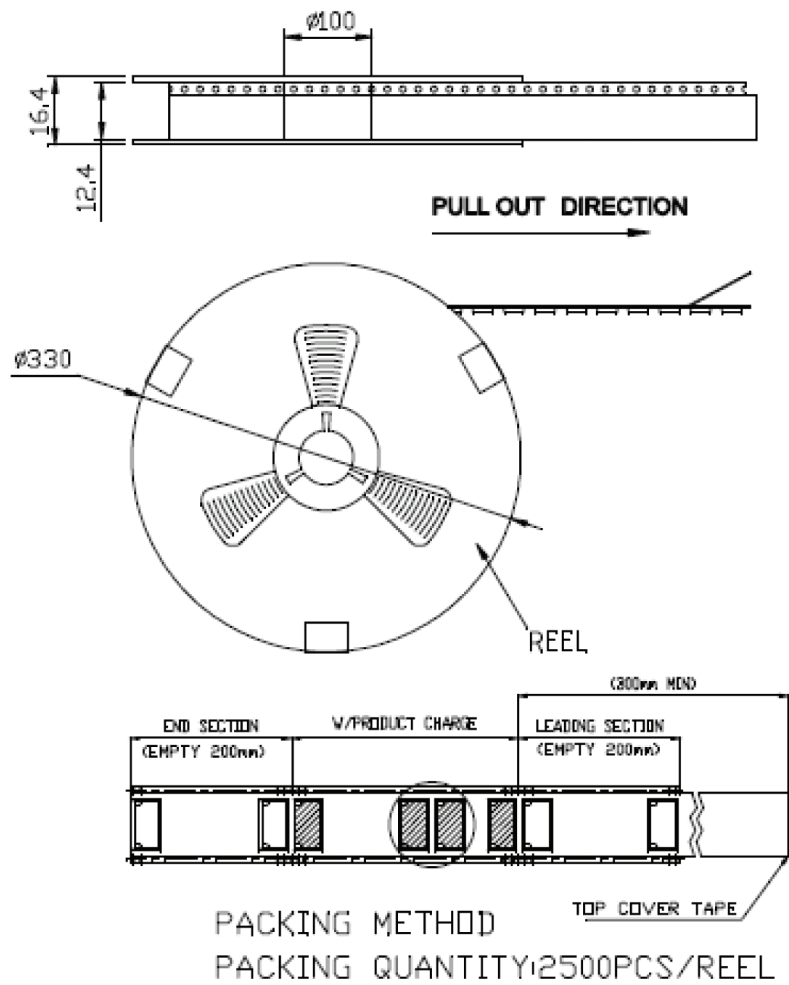
C-clip position on PWB layout



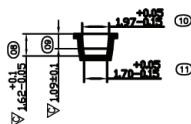
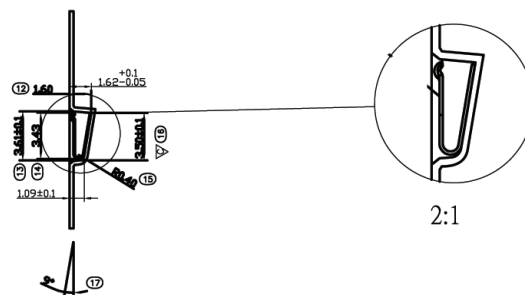
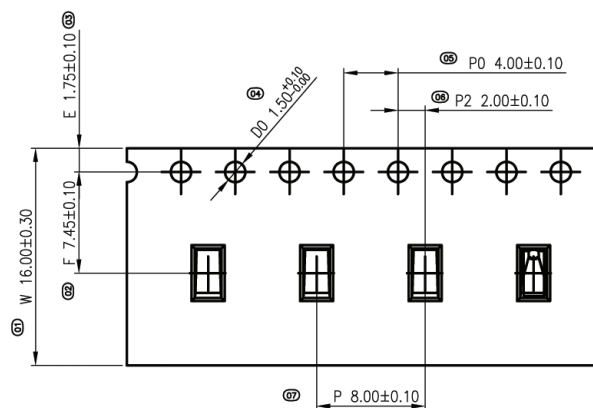
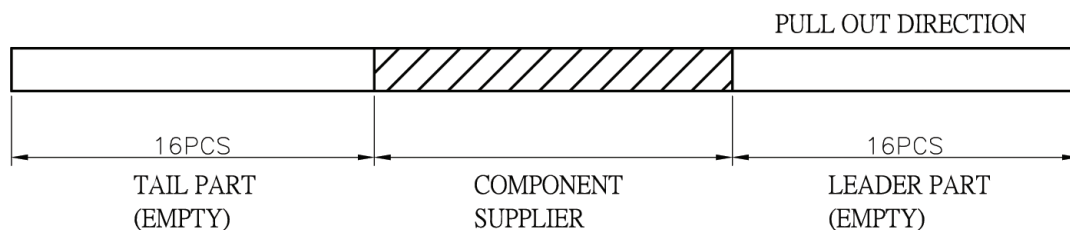
C-Clip Connector

Pulse Part Number W9908

Reel packing:



Pulse Part Number W9908



C-Clip Connector

Pulse Part Number W9908

W9908 Connector Soldering

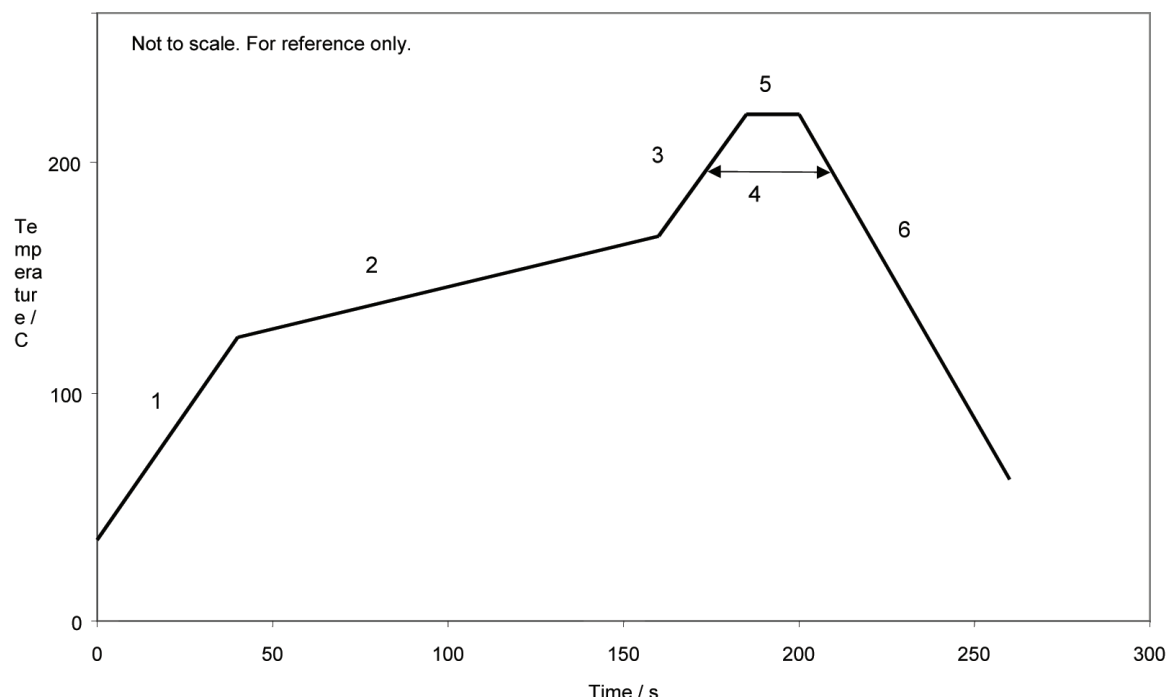
Recommendation for reflow soldering process

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s



C-Clip Connector

Pulse Part Number W9908

Figure 2 - Maximum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 60 sec
5	Time above 230°C	Max 50 sec
6	Time above 250°C	Max 10 sec
7	Peak temperature in reflow	260°C for 5 seconds
8	Temperature gradient in cooling	Max -5°C/s

